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(54) **PRINTED CIRCUIT BOARD FOR PHASED
ARRAY ANTENNA TRANSCEIVER
ASSEMBLY, TRANSCEIVER ASSEMBLY AND
RADAR**

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ABSTRACT

A printed circuit board (PCB) for a phased array antenna transceiver assembly, a transceiver assembly, and a radar are provided. The PCB includes a microwave core board layer, operating in a first frequency band, where a chip carrying area is arranged on a side of the microwave core board layer, and the chip carrying area is configured to carry a chip; a digital core board layer, operating in a second frequency band and stacked on another side of the microwave core board layer away from the chip carrying area; where an interlayer connecting path is arranged on the microwave core board layer and the digital core board layer, and the interlayer connecting path is connected to the chip carrying area; and a heat dissipation member, embedded in the digital core board layer and connected to the chip carrying area.

